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RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2800

#10/2003
AF
OK
4/25/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named
Inventor : Ramesh Sundaram et al.

Appln. No.: 10/015,045

Filed : December 11, 2001

For : GLIDE HEADS AND METHODS FOR
MAKING GLIDE HEADS

Docket No.: S01.12-0881

Group Art Unit: 2856

Examiner: Thomas
Noland

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AMENDMENT AFTER FINAL

Commissioner for Patents
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I HEREBY CERTIFY THAT THIS PAPER IS BEING
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14 DAY OF February 20 03
Douglas Z. Kvale
PATENT ATTORNEY

Sir:

This is in response to the Office Action mailed on
December 23, 2002. Please amend the above-identified application
as follows:

IN THE CLAIMS

Please cancel claims 1-10.

Please amend claims 11, 13, 15-19, 23 and 25 as follows:

C1
11. (Thrice Amended) A wafer including a glide head array
including a plurality of rows and a plurality of columns of glide
portions having air bearing surfaces formed on a surface of the
wafer and an array of glide transducers on the wafer to form a
plurality of glide heads.

C2
13. (Twice Amended) The wafer of claim 11 wherein said surface of
the wafer has a flatness less than about 3 μ m.

C3
15. (Twice Amended) The wafer of claim 11 wherein the surface of

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